SDC1204 SERIES

1. PART NO. EXPRESSION:

SDC1204-3R9YF

(a) Series code

(d) Tolerance code : $M = \pm 20\%$, $Y = \pm 30\%$

(a)

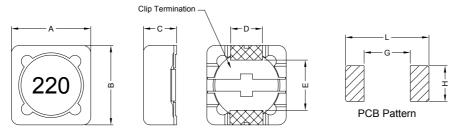
(c) (d)(e)

(b) Dimension code

(e) F: Lead Free

(c) Inductance code : 3R9 = 3.9uH

2. CONFIGURATION & DIMENSIONS:



Unit:m/m

Α	В	С	D	E	G	Н	L
12.0±0.3	12.0±0.3	5.0 Max.	5.0±0.2	7.6±0.2	7.0 Ref.	5.4 Ref.	12.6 Ref.

3. SCHEMATIC:



4. GENERAL SPECIFICATION:

a) Temp. rise : 40°C Max.b) Ambient temp. : 25°C

c) Rated current : Base on temp. rise & $\Delta L/L0A = 30\%$ Max.

d) Operating temp. : -25°C to +85°C e) Storage temp. : -25°C to +85°C



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5. ELECTRICAL CHARACTERISTICS:

Part No.	Inductance (μH)	Test Frequency (Hz)	DCR (Ω) Max.	IDC (A) Max.
SDC1204-3R9YF	3.9 ±30%	1V / 100K	0.015	6.50
SDC1204-4R7YF	4.7 ±30%	1V / 100K	0.018	5.70
SDC1204-6R8YF	6.8 ±30%	1V / 100K	0.023	4.90
SDC1204-8R2YF	8.2 ±30%	1V / 100K	0.026	4.60
SDC1204-100MF	10 ±20%	1V / 100K	0.028	4.50
SDC1204-120MF	12 ±20%	1V / 100K	0.038	4.00
SDC1204-150MF	15 ±20%	1V / 100K	0.050	3.20
SDC1204-180MF	18 ±20%	1V / 100K	0.057	3.10
SDC1204-220MF	22 ±20%	1V / 100K	0.066	2.90
SDC1204-270MF	27 ±20%	1V / 100K	0.080	2.80
SDC1204-330MF	33 ±20%	1V / 100K	0.097	2.70
SDC1204-390MF	39 ±20%	1V / 100K	0.132	2.10
SDC1204-470MF	47 ±20%	1V / 100K	0.160	1.90
SDC1204-560MF	56 ±20%	1V / 100K	0.190	1.80
SDC1204-680MF	68 ±20%	1V / 100K	0.220	1.50
SDC1204-820MF	82 ±20%	1V / 100K	0.260	1.30
SDC1204-101MF	100 ±20%	1V / 100K	0.308	1.20
SDC1204-121MF	120 ±20%	1V / 100K	0.380	1.10
SDC1204-151MF	150 ±20%	1V / 100K	0.530	0.95
SDC1204-181MF	180 ±20%	1V / 100K	0.620	0.85
SDC1204-221MF	220 ±20%	1V / 100K	0.700	0.80
SDC1204-271MF	270 ±20%	1V / 100K	0.870	0.60
SDC1204-331MF	330 ±20%	1V / 100K	0.990	0.50



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6. RELIABILITY AND TEST CONDITIONS:

ITEM	PERFORMANCE	TEST CONDITION		
Electrical Characteristics T	est			
Inductance	Refer to standard electrical characteristics list	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR meter.		
DCR		CH16502, Agilent33420A Micro-Ohm Meter.		
Heat Rated Current (Irms)		Irms(A) will cause the coil temperature rise approximately ΔT=40°C without core loss 1. Applied the allowed DC current 2. Temperature measured by digital surface thermometry		
Saturation Current (Isat)		Isat(A) will cause Lo to drop approximately 20% max.		
Mechanical Performance T	- Test			
Solderability Test	More than 90% of the terminal electrode should be covered with solder. Preheating Dipping Natural cooling 150°C 150°C 150°C 150°C 150°C	Preheat: 150°C, 60sec. Solder: Sn-Ag3.0-Cu0.5 Solder Temperature: 230±5°C Flux for lead free: rosin Dip Time: 4±1sec.		
Solder Heat Resistance	Appearance : No significant abnormality Inductance change : Within ±20% Preheating Dipping Natural cooling 150°C 150°C 150°C 150°C 150°C 150°C 150°C 150°C	Preheat: 150°C, 60sec. Solder: Sn-Ag3.0-Cu0.5 Solder Temperature: 260±5°C Flux for lead free: rosin Dip Time: 10±0.5sec.		
Reliability Test				
High Temperature Life Test Low Temperature		Temperature : 85±5°C Time : 500±12 hours Measure at room temperature after placing for 2 to 3 hr. Temperature : -25±5°C		
Life Test 1. Appearance : No damage 2. Inductance : Within ±20% of initial valu		Time: 500±12 hours Measure at room temperature after placing for 2 to 3 hr		
Thermal Shock	No disconnection or short circuit.	Conditions of 1 cycle. Step Temperature (°C) Times (min.) 1		
Humidity Resistance	Appearance : No damage Inductance : Within ±20% of initial value. No disconnection or short circuit.	Temperature: 40±5°C Humidity: 90% to 95% Applied Current: Rated Curent Time: 500±12 hours Measure at room temperature after placing for 2 to 3 hrs.		



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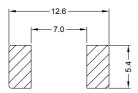
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PG. 3



7. SOLDERIND AND MOUNTING:

7-1. Recommended PC Board Pattern



7-2. Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-2.1 Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

7-2.2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note:

- a) Preheat circuit and products to 150°C.
- b) 280°C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 3 secs.

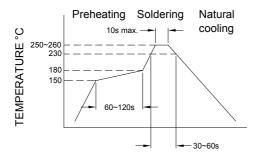


Figure 1. Re-flow Soldering

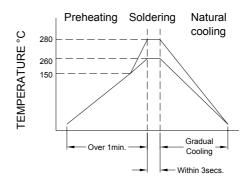


Figure 2. Iron Soldering



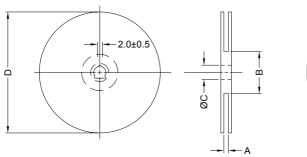
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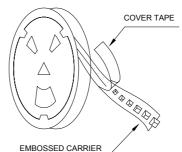


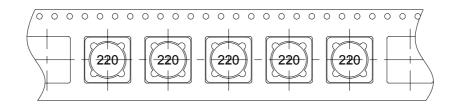
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8. PACKAGING INFORMATION:

8-1. Tape and Reel Dimension







Туре	Type A(mm)		C(mm)	D(mm)	
13" x 24mm	24.0±0.1	100±1	13±0.5	330	

8-3. Packaging Quantity

Size	SDC1204	
Chip / Reel	750	
Reel Style	13" x 24mm	



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